

SUBMINIATURE SOLID STATE LAMP

Part Number: AM2520SGC09

Super Bright Green

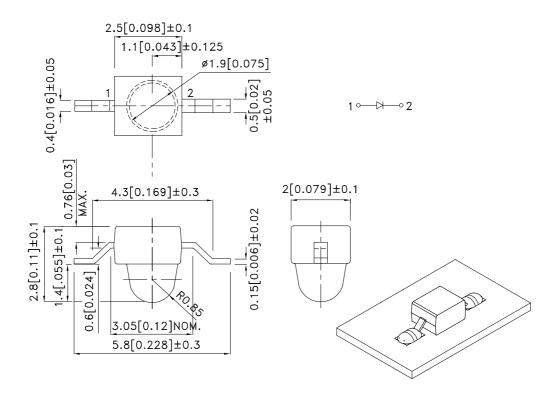
Features

- SUBMINIA TURE PACKAGE.
- WIDE VIEWING ANGLE.
- Z-BEND LEAD.
- LONG LIFE SOLID STATE RELIABILITY.
- LOW PACKAGE PROFILE.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- PACKAGE: 1000PCS / REEL.
- RoHS COMPLIANT.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.
- 5. The device has a single mounting surface. The device must be mounted according to the specifications.





 SPEC NO: DSAD1290
 REV NO: V.6
 DATE: MAY/08/2007
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 APPROVED: WYNEC
 CHECKED: Allen Liu
 DRAWN: Y.L.LI
 ERP: 1202000634

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
AM2520SGC09	Super Bright Green (GaP)	WATER CLEAR	36	80	20°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	V _F =0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Green		10	uA	V _R =5V

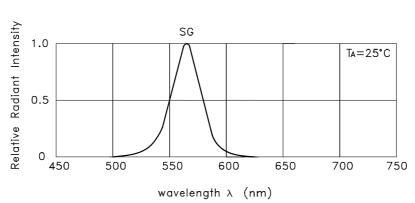
1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

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Parameter	Super Bright Green	Units			
Power dissipation	62.5	mW			
DC Forward Current	25	mA			
Peak Forward Current [1]	140	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

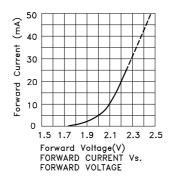
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

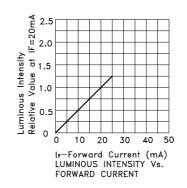
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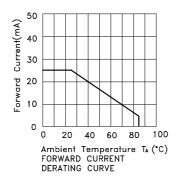


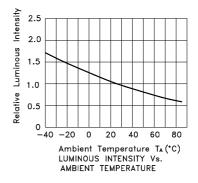
RELATIVE INTENSITY Vs. WAVELENGTH

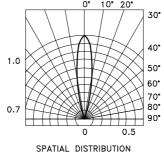
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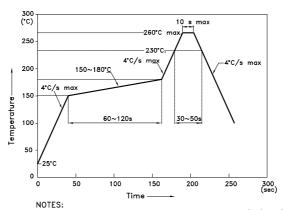


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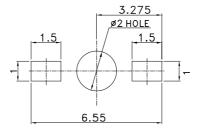
Reflow Soldering Profile For Lead-free SMT Process.



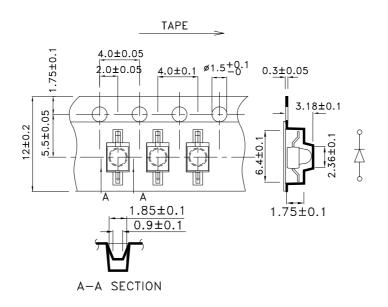
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



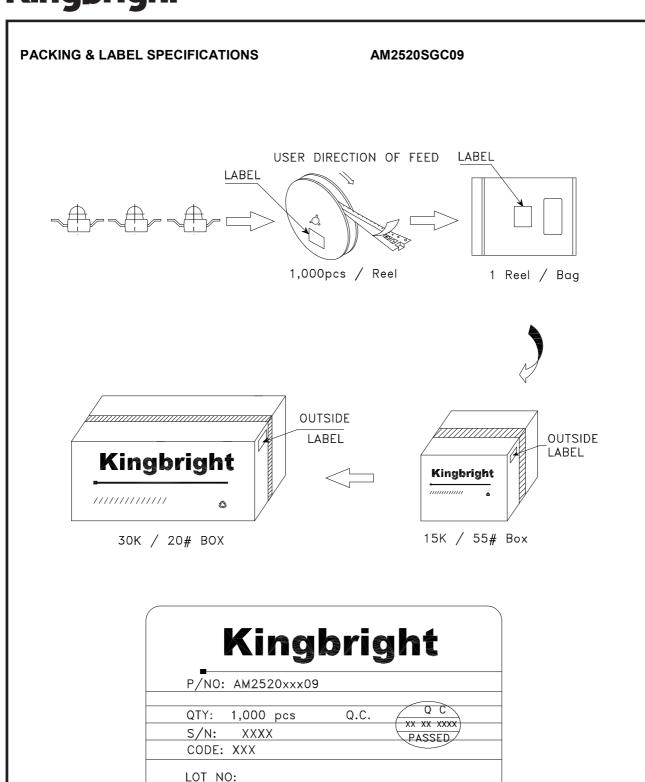
Tape Specifications (Units: mm)



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RoHS Compliant

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